

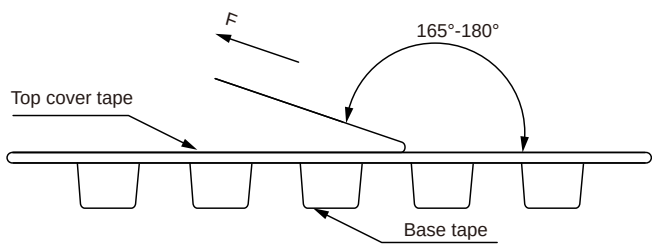
Soldering Reflow:

Packaging Information:

Tape Dimension:

Series	A0 (mm)	B0 (mm)	D (mm)	P0 (mm)	P1 (mm)	W (mm)	K0 (mm)	E (mm)	T (mm)
MDTA20161A	1.9 ± 0.1	2.3 ± 0.1	1.5 ± 0.1	4.0 ± 0.1	4 ± 0.1	8.0 ± 0.3	1.2 ± 0.1	1.75 ± 0.1	0.25 ± 0.05

Peel force of top cover tape:



The peel force of top cover tape shall be between 0.1 to 0.98 N

Reel Dimension: [mm]

Cautions and Warnings:

Storage Conditions:

- The storage period is within 12 months after the completion of production. Be sure to follow the storage conditions (temperature: -5 to 35°C, humidity: 75% RH Max). If the storage period elapses, the soldering of the terminal electrodes may deteriorate. The warranty period is one year.
- Product should not be exposed to environment with high temperature, high humidity, dust, corrosive gas and etc.
- Products should be handled with care to avoid damage or contamination from perspiration and skin oils.
- Please always handle products carefully to prevent any damage caused by dropping down or inappropriate removing.

Operation Instructions:

- Self heating (temperature increase) occurs when the power is turned ON, so the tolerance should be sufficient for the set thermal design.
- Before soldering, be sure to preheat components. The preheating temperature should be set so that the temperature difference between the solder temperature and chip temperature does not exceed 150°C.
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